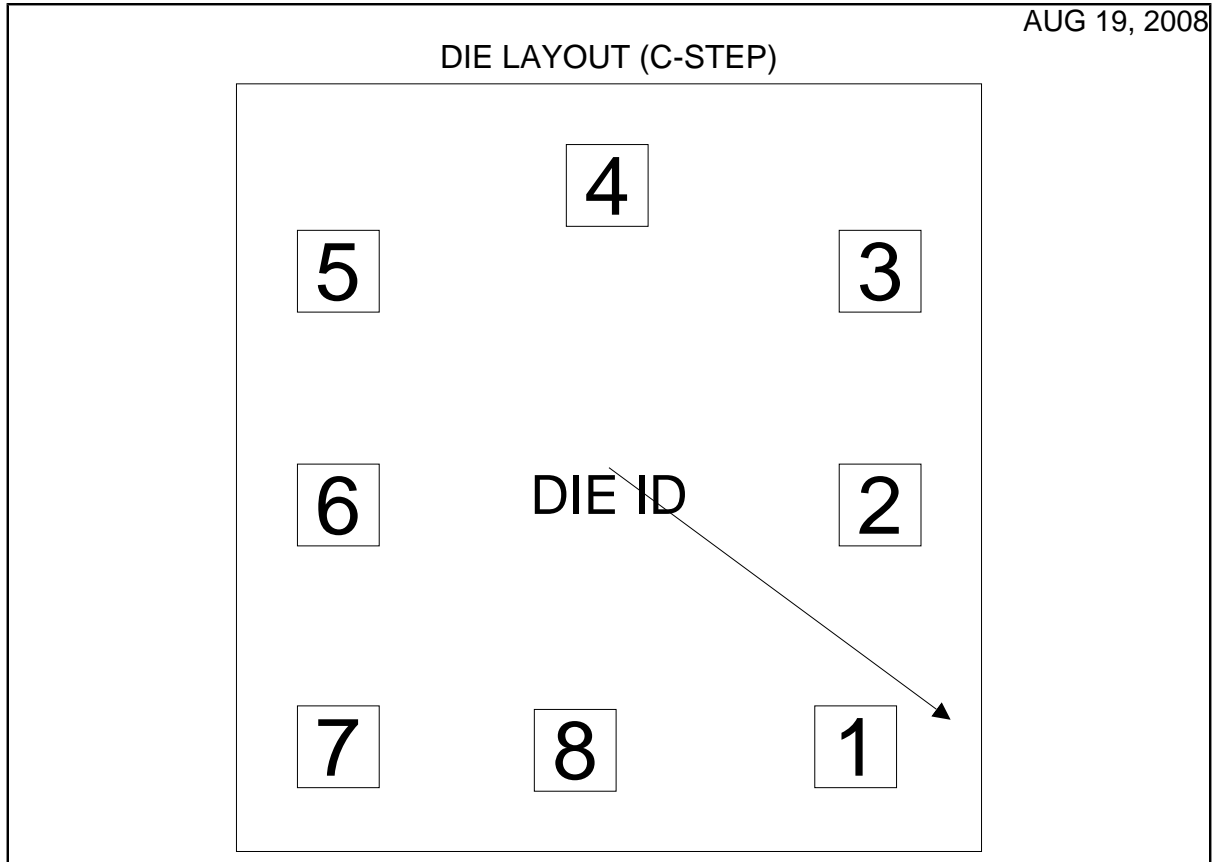


LM193 MDE MCD2790A
LOW POWER LOW OFFSET VOLTAGE DUAL COMPARATORS



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM193	Bond Pad Opening Size (min)	92.00µm x 92.00µm
Die Step	C	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	838.2µm x 863.6µm 33.0mils x 34.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	263.00µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(C-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
Output A	1	277	-314	92	x	92
Input A -	2	305	-42	92	x	92
Input A +	3	305	221	92	x	92
Gnd	4	-2	317	92	x	92
Input B +	5	-304	221	92	x	92
Input B -	6	-304	-42	92	x	92
Output B	7	-304	-314	92	x	92
V +	8	-38	-318	92	x	92

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